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PATENT

IN THE UNITED STATES PATENT OFFICE

Serial No.: 09/831,763

Filed: May 11, 2001

For: METHOD OF ELECTROLYTICALLY  
FORMING CONDUCTOR STRUCTURES  
FROM HIGHLY PURE COPPER WHEN  
PRODUCING INTEGRATED CIRCUITS

Inventors: Heinrich Meyer, Andreas Thies

Atty Doc. No.: 71-01

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Post Office as first class mail postage prepaid in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on January 15, 2002.

*John F. McNulty*  
John F. McNulty, Reg. No. 23,028  
Dated: January 15, 2002

**COVER LETTER WITH CERTIFICATE OF MAILING**

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Dear Sir:

Enclosed and attached hereto are the following documents;

- (1) International Preliminary Examination Report, dated October 30, 2000 ( English Translation);
- (2) Cover Letter With Certificate of Mailing; and
- (3) Paul & Paul postcard to be returned by the PTO.

THE COMMISSIONER IS HEREBY AUTHORIZED TO CHARGE ANY ADDITIONAL FEES ASSOCIATED WITH THIS COMMUNICATION, OR CREDIT ANY OVERPAYMENT, TO PAUL & PAUL DEPOSIT ACCOUNT NO. 16-0750, ORDER NO. 0923.

Respectfully submitted,

*John P. McNulty*  
John P. McNulty  
Reg. No. 23,028  
Paul & Paul  
2900 Two Thousand Market St.  
Philadelphia, PA 19103  
(215) 568-4900

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